

EPS Webinar Series 2020/21

The Evolution of Lead-free Solder Alloys

Dr. HongWen Zhang is Manager of the Alloy Group in Indium Corporation's Research & Development Department. His focus is on the development of lead-free solder materials and the associated technologies for high-temperature and high-reliability applications. He and Dr. Ning-Cheng Lee invented the mixed powder solder technique to combine the merits of constituents to improve wetting, reduce processing temperatures, modify the bonding interface, and control the joint's morphology, thus improving the reliability.



Dr. HongWen Zhang

Manager, Alloy Group
Indium Corporation's R&D
Department.

JOIN US FOR THIS UPCOMING WEBINAR

REGISTER NOW

(Click the link for registration)

**E-certificates will be provided to participant*

Date: 16th December 2020 (Wednesday)
Time: 9.00-10.00 a.m (M'sia Time, GMT +8:00)
Platform: CISCO WebEx

Join us on the 16th December, Wednesday and learn on the evolution of lead-free solder,

- ✓ The first generation high-Ag SAC solders.
 - ✓ The low Ag/zero Ag Sn-rich solders.
 - ✓ The high-reliable SAC solders.
- ✓ The low temperature lead-free solders and.
- ✓ High temperature lead-free bonding materials.

In each session, the market need, the pros and cons of the representative materials in each group are discuss.

- It is **FREE!** Enroll yourself and join us in this exciting webinar. See you there!